



RF360  
Europe GmbH

## Data sheet

Micro-acoustic filter  
GPS L5

Series/type:	B7505
Ordering code:	B39122B7505L210
Date:	August 19, 2019
Version:	2.1

DCN: 80-PA243-343 Rev. B

RF360 products mentioned within this document are products of RF360 Europe GmbH and other subsidiaries of RF360 Holdings Singapore Pte. Ltd. (collectively, the "RF360 Subsidiaries").

RF360 Europe GmbH, Anzinger Str. 13, München, Germany

© 2019 RF360 Europe GmbH and/or its affiliated companies. All rights reserved.

These materials, including the information contained herein, may be used only for informational purposes by the customer. The RF360 Subsidiaries assume no responsibility for errors or omissions in these materials or the information contained herein. The RF360 Subsidiaries reserve the right to make changes to the product(s) or information contained herein without notice. The materials and information are provided on an AS IS basis, and the RF360 Subsidiaries assume no liability and make no warranty or representation, either expressed or implied, with respect to the materials, or any output or results based on the use, application, or evaluation of such materials, including, without limitation, with respect to the non-infringement of trademarks, patents, copyrights or any other intellectual property rights or other rights of third parties.

No use of this documentation or any information contained herein grants any license, whether express, implied, by estoppel or otherwise, to any intellectual property rights, including, without limitation, to any patents owned by QUALCOMM Incorporated or any of its subsidiaries.

Not to be used, copied, reproduced, or modified in whole or in part, nor its contents revealed in any manner to others without the express written permission of RF360 Europe GmbH.

Qualcomm is a trademark of Qualcomm Incorporated, registered in the United States and other countries. Other product and brand names may be trademarks or registered trademarks of their respective owners.

This technical data may be subject to U.S. and international export, re-export, or transfer ("export") laws. Diversion contrary to U.S. and international law is strictly prohibited.



RF360 Europe GmbH  
A Qualcomm – TDK Joint Venture

## Data sheet

Micro-acoustic filter  
GPS L5

Series/type:	B7505
Ordering code:	B39122B7505L210
Date:	August 19, 2019
Version:	2.1

DCN: 80-PA243-343 Rev. B

RF360 products mentioned within this document are products of RF360 Europe GmbH and other subsidiaries of RF360 Holdings Singapore Pte. Ltd. (collectively, the "RF360 Subsidiaries").

RF360 Holdings Singapore Pte. Ltd. is a joint venture of Qualcomm Global Trading Pte. Ltd. and EPCOS AG.

RF360 Europe GmbH, Anzinger Str. 13, München, Germany

© 2019 RF360 Europe GmbH and/or its affiliated companies. All rights reserved.

These materials, including the information contained herein, may be used only for informational purposes by the customer. The RF360 Subsidiaries assume no responsibility for errors or omissions in these materials or the information contained herein. The RF360 Subsidiaries reserve the right to make changes to the product(s) or information contained herein without notice. The materials and information are provided on an AS IS basis, and the RF360 Subsidiaries assume no liability and make no warranty or representation, either expressed or implied, with respect to the materials, or any output or results based on the use, application, or evaluation of such materials, including, without limitation, with respect to the non-infringement of trademarks, patents, copyrights or any other intellectual property rights or other rights of third parties.

No use of this documentation or any information contained herein grants any license, whether express, implied, by estoppel or otherwise, to any intellectual property rights, including, without limitation, to any patents owned by QUALCOMM Incorporated or any of its subsidiaries.

Not to be used, copied, reproduced, or modified in whole or in part, nor its contents revealed in any manner to others without the express written permission of RF360 Europe GmbH.

Qualcomm is a trademark of Qualcomm Incorporated, registered in the United States and other countries. Other product and brand names may be trademarks or registered trademarks of their respective owners.

This technical data may be subject to U.S. and international export, re-export, or transfer ("export") laws. Diversion contrary to U.S. and international law is strictly prohibited.

## Table of contents

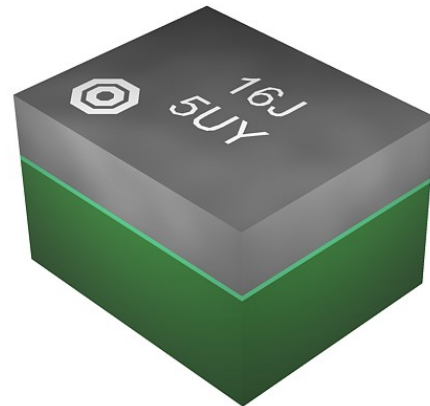
1	<a href="#">Application</a>	4
2	<a href="#">Features</a>	4
3	<a href="#">Package</a>	5
4	<a href="#">Pin configuration</a>	5
5	<a href="#">Matching circuit</a>	6
6	<a href="#">Characteristics</a>	7
7	<a href="#">Maximum ratings</a>	8
8	<a href="#">Transmission coefficient</a>	9
9	<a href="#">Reflection coefficients</a>	10
10	<a href="#">Packing material</a>	11
11	<a href="#">Marking</a>	15
12	<a href="#">Soldering profile</a>	16
13	<a href="#">Annotations</a>	17
14	<a href="#">Cautions and warnings</a>	18
15	<a href="#">Important notes</a>	19

## 1 Application

- Low-loss RF GNSS L5 filter
- Usable passbands: 20.46 MHz for GPS L5
- Very low insertion attenuation
- High out of band selectivity
- Filter impedance 50  $\Omega$
- Unbalanced to unbalanced operation
- No matching network required for operation at 50  $\Omega$

## 2 Features

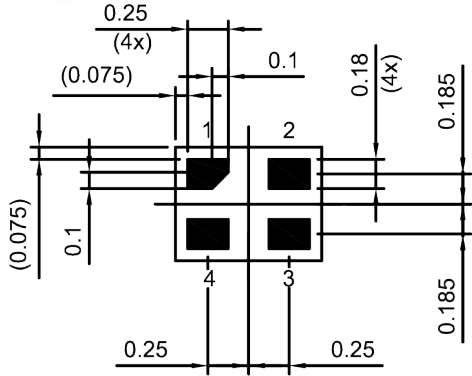
- Package size 0.9 mm x 0.7 mm
- Package height 0.50 mm (max)
- Approximate weight 1mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)



**Figure 1:** Picture of component with example of product marking.

**3 Package**

BOTTOM VIEW

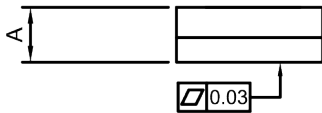


Pad and pitch tolerance ±0.05

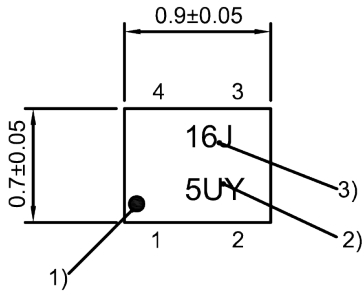
**4 Pin configuration**

- 1 Input
- 3 Output
- 2, 4 Ground

SIDE VIEW

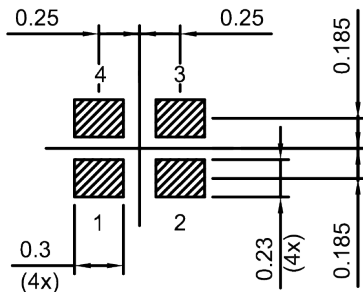


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example fo encoded filter type number

Land pattern  
THRU VIEW



Landing pad tolerance -0.02

**Figure 2:** Drawing of package with package height A = 0.50 mm (max). See Sec. Package information (p. 21).

5 Matching circuit

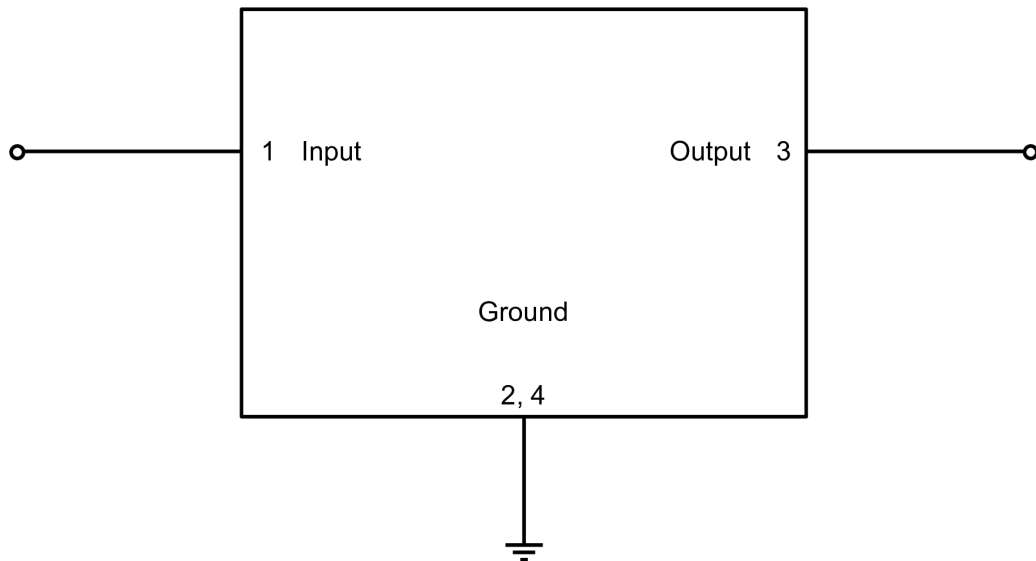


Figure 3: Schematic of matching circuit. No external matching components required.



## 6 Characteristics

Temperature range for specification	$T_{SPEC}$	= -30 °C ... +85 °C
Input terminating impedance	$Z_{IN}$	= 50 $\Omega$
Output terminating impedance	$Z_{OUT}$	= 50 $\Omega$

Characteristics		min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
<b>Center frequency</b>	$f_c$	—	1176.45	—	MHz
<b>Insertion Loss</b>	$\alpha$				
	1166.22... 1186.68 MHz	—	0.9 <sup>1)</sup>	1.3	dB
<b>VSWR</b>	VSWR				
@ input port	1166.22... 1186.68 MHz	—	1.5	2.0	
@ output port	1166.22... 1186.68 MHz	—	1.5	2.0	
<b>Attenuation</b>	$\alpha$				
	638... 698 MHz	50	58	—	dB
	698... 748 MHz	50	58	—	dB
	777... 798 MHz	50	59	—	dB
	807... 915 MHz	50	59	—	dB
	925... 960 MHz	50	62	—	dB
	1330... 1427 MHz	29	54	—	dB
	1427... 1463 MHz	48	57	—	dB
	1640... 1695 MHz	29	56	—	dB
	1695... 1710 MHz	45	56	—	dB
	1710... 1785 MHz	45	54	—	dB
	1850... 2025 MHz	48	55	—	dB
	2300... 2400 MHz	45	50	—	dB
	2400... 2483 MHz	45	49	—	dB
	2496... 2690 MHz	45	48	—	dB
	3400... 3800 MHz	35	44	—	dB
	4400... 4900 MHz	35	44	—	dB
	5150... 5925 MHz	35	41	—	dB

<sup>1)</sup> Typical value average over indicated frequency range.

## 7 Maximum ratings

Storage temperature	$T_{STG}^{2)} = -40\text{ °C} \dots +85\text{ °C}^{1)}$	
DC voltage	$ V_{DC}  = 5.0\text{ V (max.)}^{3)}$	
ESD voltage	$V_{ESD}^{4)} = 100\text{ V (max.)}$	Machine model.
	$V_{ESD}^{5)} = 200\text{ V (max.)}$	Human body model.
	$V_{ESD}^{6)} = 600\text{ V (max.)}$	Charged device model.
Input power @ input port:		
915 MHz	$P_{IN} = 23\text{ dBm}$	GSM signal duty cycle 1:8 for 5000 h @ 50 °C. Effective power in On-state.
915 MHz	$P_{IN} = 15\text{ dBm}$	Continuous wave for 5000 h @ 55 °C.
1428 MHz	$P_{IN} = 15\text{ dBm}$	Continuous wave for 5000 h @ 55 °C.

<sup>1)</sup> Extended upperlimit: 96h@125°C acc. to IEC 60068-2-2 Bb.

<sup>2)</sup> Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

<sup>3)</sup> 168h Damp Heat Steady State acc. IEC 60068-2-67 Cy.

<sup>4)</sup> According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

<sup>5)</sup> According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

<sup>6)</sup> According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

8 Transmission coefficient

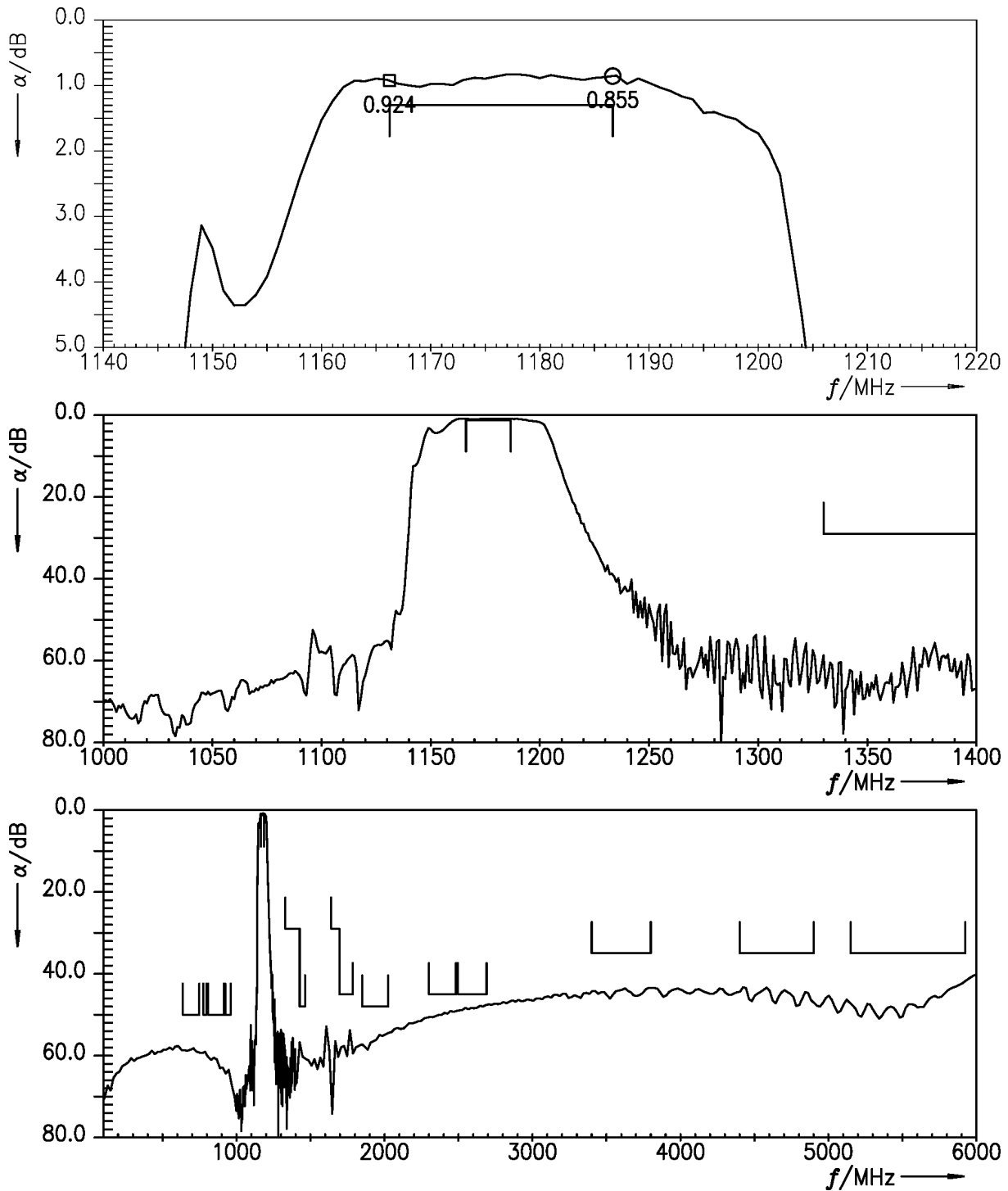


Figure 4: Attenuation.

9 Reflection coefficients

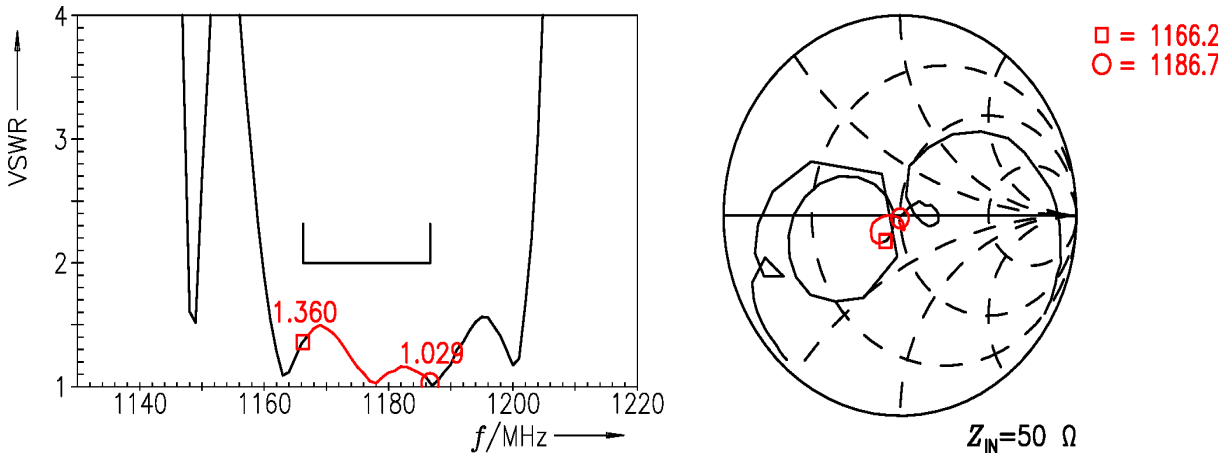


Figure 5: Reflection coefficient at input port.

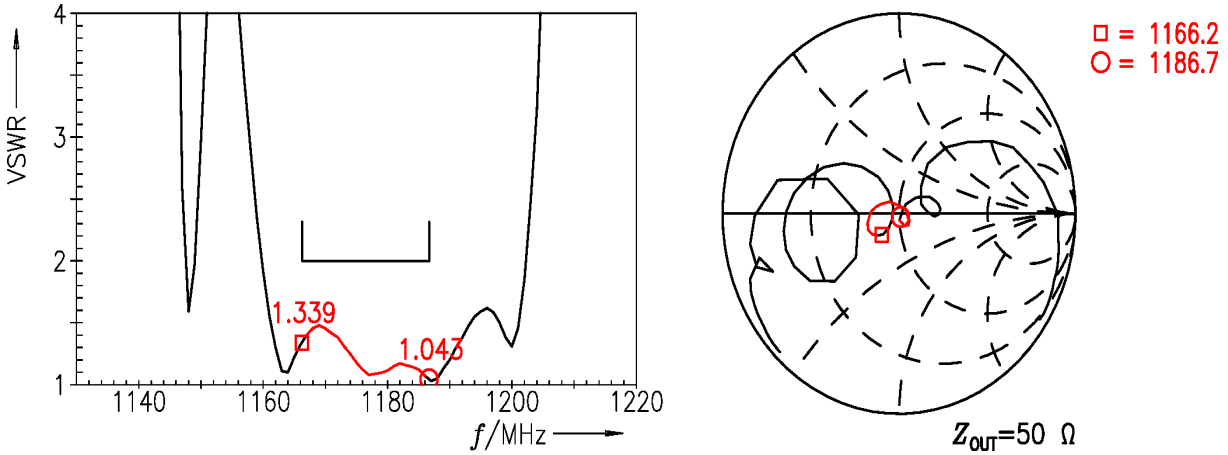
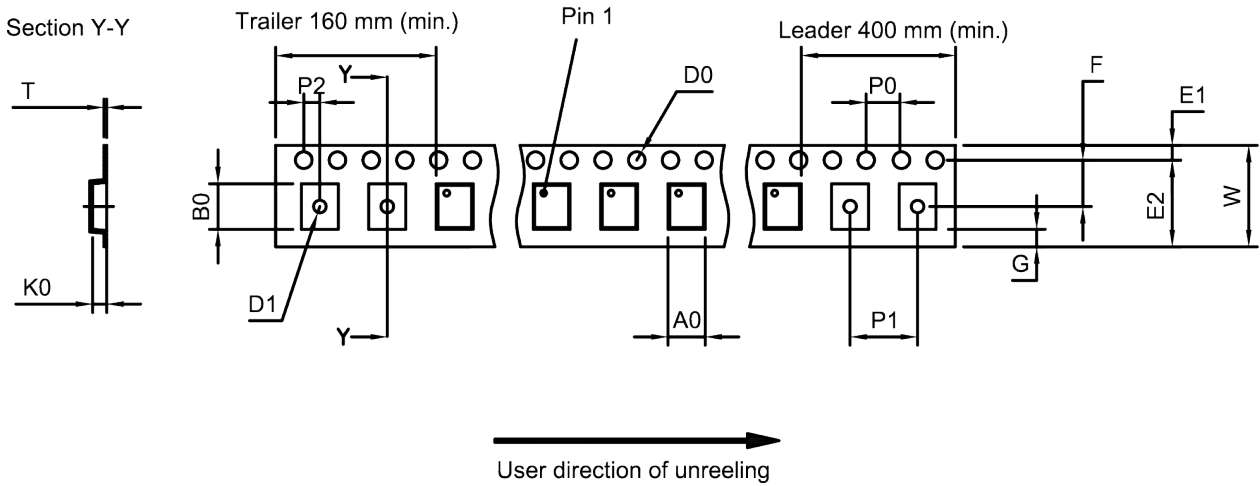


Figure 6: Reflection coefficient at output port.

10 Packing material

10.1 Tape



**Figure 7:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A <sub>0</sub>	0.85±0.05 mm	E <sub>2</sub>	0.625 mm (min.)	P <sub>1</sub>	2.0±0.05 mm
B <sub>0</sub>	1.05±0.05 mm	F	3.5±0.05 mm	P <sub>2</sub>	2.0±0.05 mm
D <sub>0</sub>	1.5+0.05 mm	G	0.75 mm (min.)	T	0.25±0.02 mm
D <sub>1</sub>	0.4±0.05 mm	K <sub>0</sub>	0.69±0.03 mm	W	8.2±0.1 mm
E <sub>1</sub>	1.75±0.1 mm	P <sub>0</sub>	4.0±0.1 mm		

**Table 1:** Tape dimensions.

10.2 Reel with diameter of 180 mm

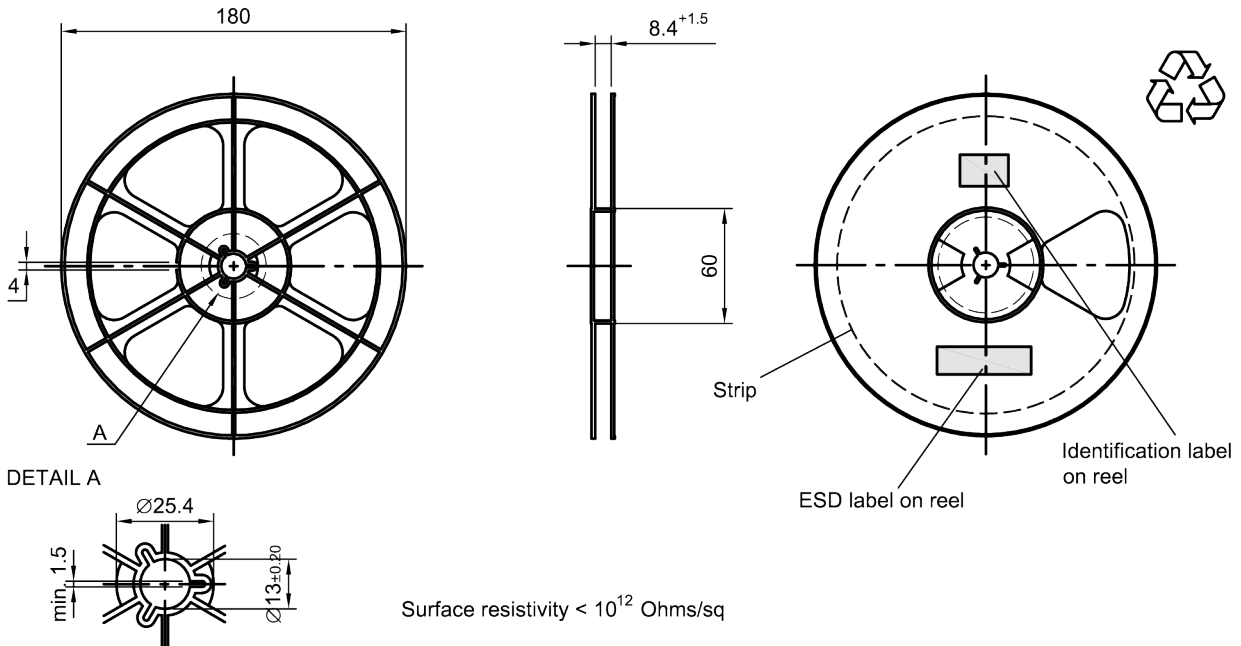


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]  
X = 220+5  
Y = 235+5  
Sealing area 10±3

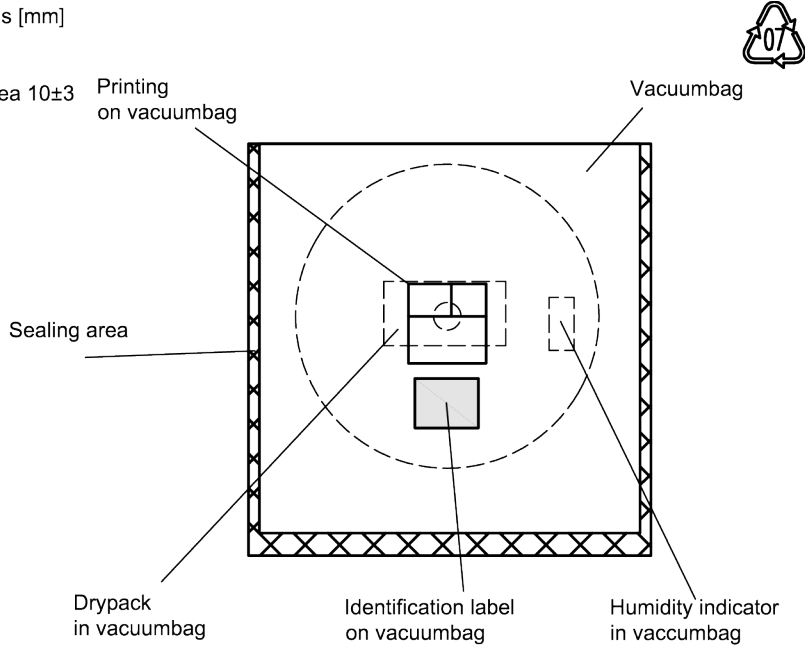
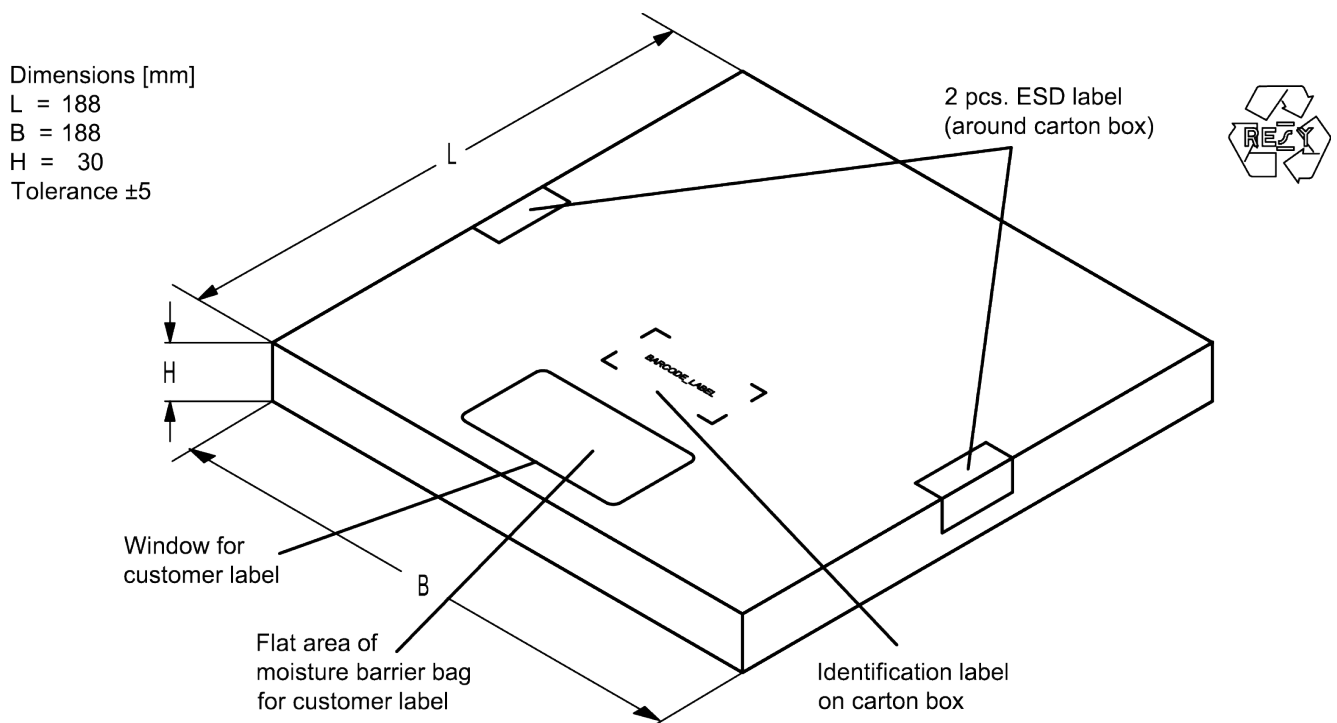


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.



**Figure 10:** Drawing of folding box for reel with diameter of 180 mm.

## 10.3 Reel with diameter of 330 mm



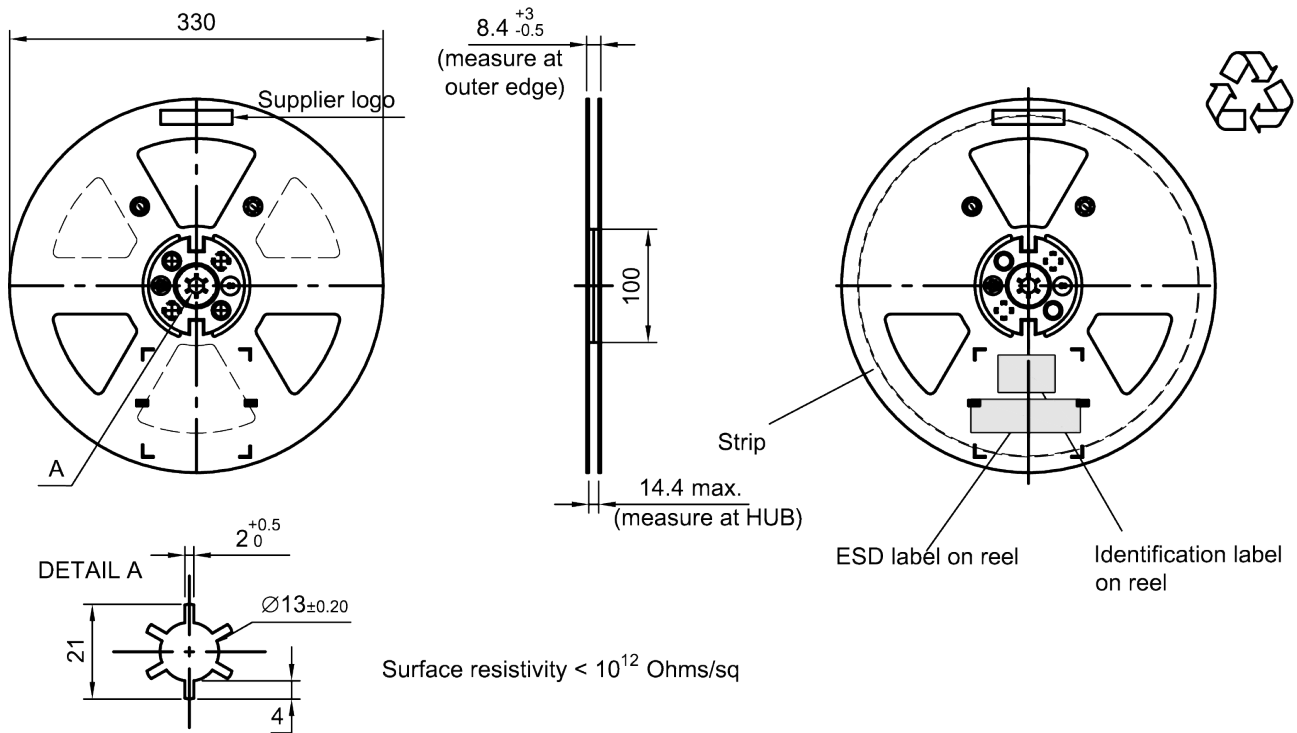


Figure 11: Drawing of reel (first-angle projection) with diameter of 330 mm.

Dimensions [mm]

X = 400±5

Y = 418±5

Sealing area 10±3

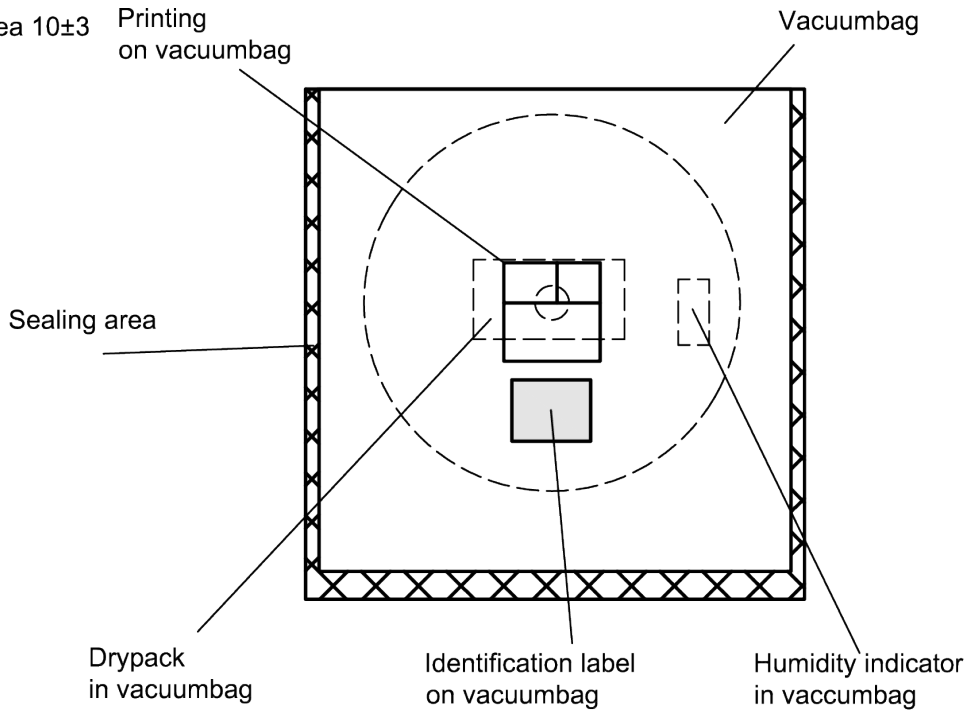


Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

Dimensions [mm]

L = 335

B = 338

H = 36 ( for 8 mm tape width)

40 ( for 12 mm tape width)

Tolerance ±5

2 pcs. ESD label  
(around carton box)

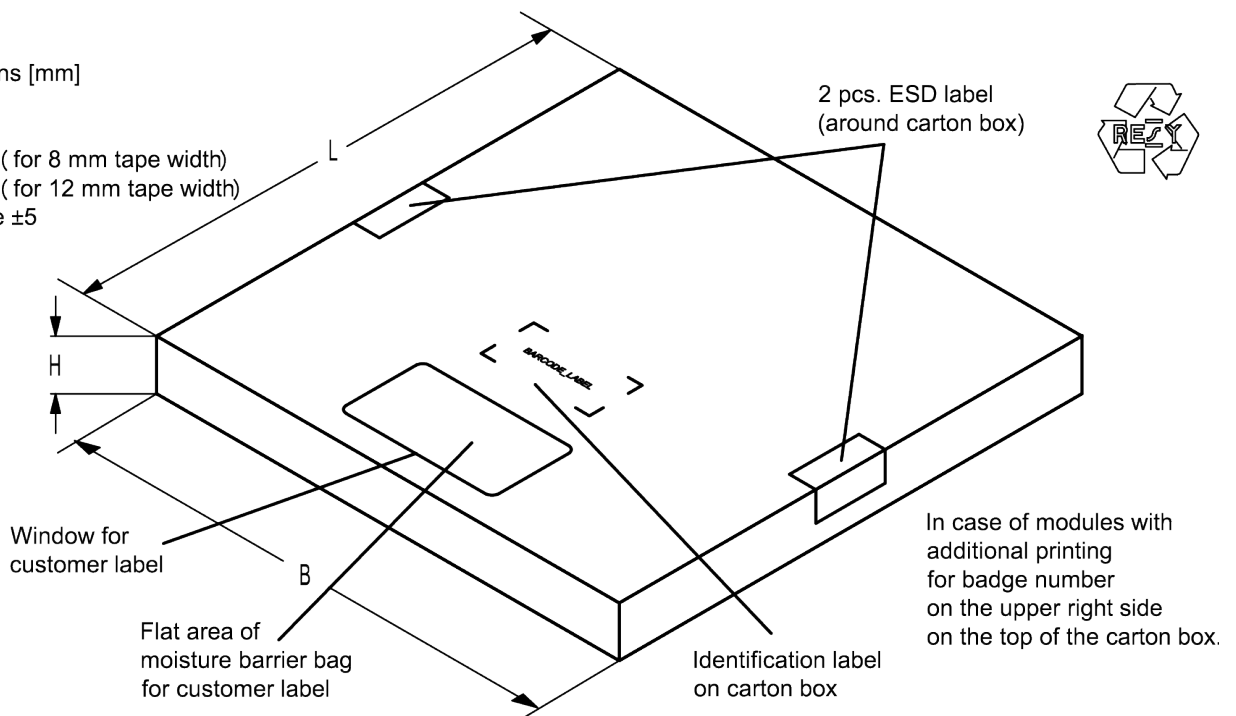


Figure 13: Drawing of folding box for reel with diameter of 330 mm.

**11 Marking**

Products are marked with product type number and lot number encoded according to Table 2:

■ **Type number:**

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,  
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding	type number marking on device	in decimal code.
	<b>16J</b>	<b>1234</b>
	$1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0$	<b>1234</b>

The BASE32 code for product type B7505 is 7AH.

■ **Lot number:**

The last 5 digits of the lot number, e.g., **12345**,  
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding	lot number marking on device	in decimal code.
	<b>5UY</b>	<b>12345</b>
	$5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0$	<b>12345</b>

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

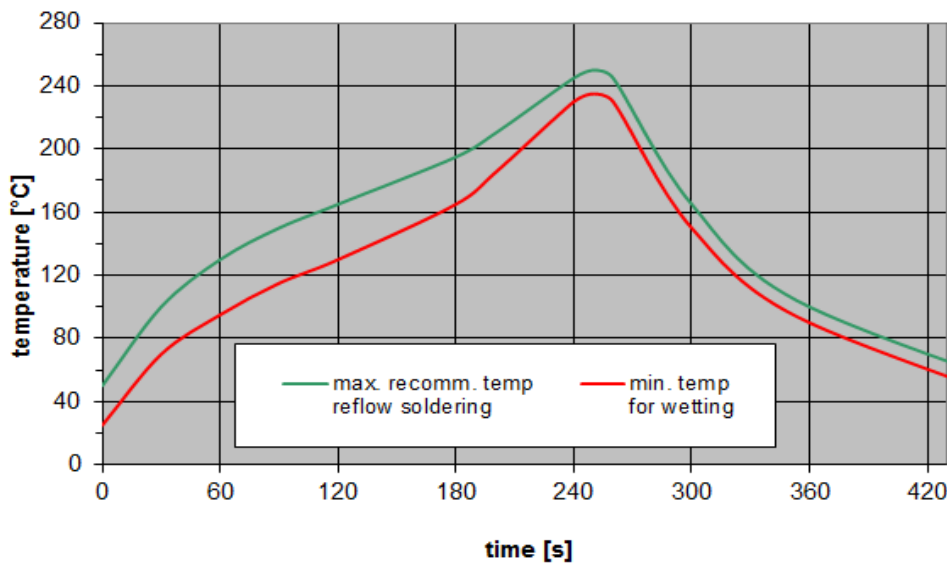
**Table 2:** Lists for encoding and decoding of marking.

## 12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3<sup>rd</sup> edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220$ °C	30 s to 70 s
$T > 230$ °C	min. 10 s
$T > 245$ °C	max. 20 s
$T \geq 255$ °C	–
peak temperature $T_{peak}$	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature $T$	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 14:** Recommended reflow profile for convection and infrared soldering – lead-free solder.

### 13 Annotations

#### 13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

#### 13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

#### 13.3 Ordering codes and packing units

Ordering code	Packing unit
B39122B7505L210	15,000 pcs
B39122B7505L210S 5	5,000 pcs

**Table 4:** Ordering codes and packing units.

## 14 Cautions and warnings

### 14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under [www.rf360jv.com/orderingcodes](http://www.rf360jv.com/orderingcodes).

### 14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

### 14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

### 14.4 Package information

#### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

#### Projection method

Unless otherwise specified first-angle projection is applied.

## 15 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet ([www.rf360jv.com/material](http://www.rf360jv.com/material)). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available.  
The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.



单击下面可查看定价，库存，交付和生命周期等信息

[>>Qualcomm-RF360](#)